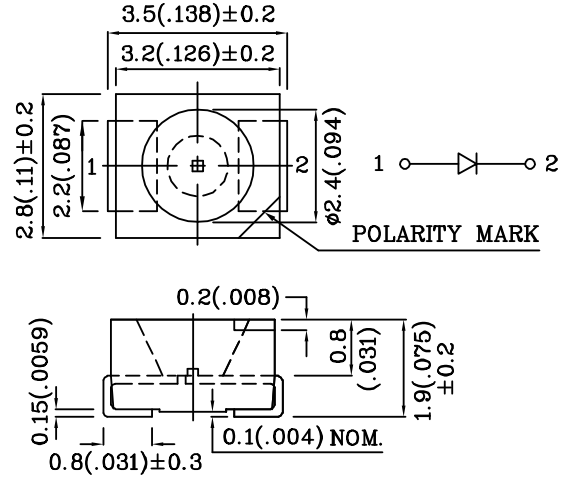


PRELIMINARY SPEC

Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- PACKAGE : 1500PCS / REEL.
- BLACK CASE.
- ROHS COMPLIANT.



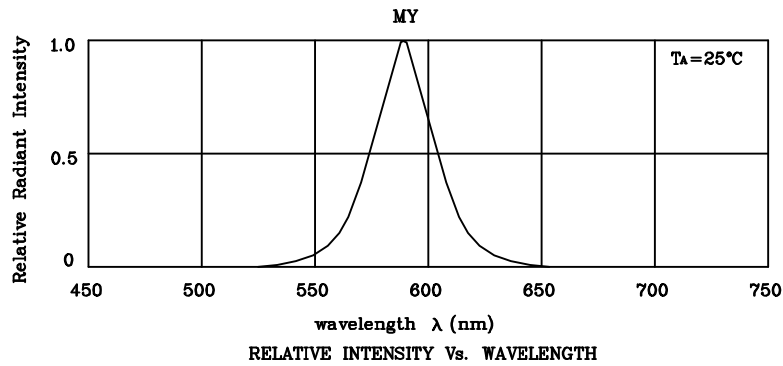
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.

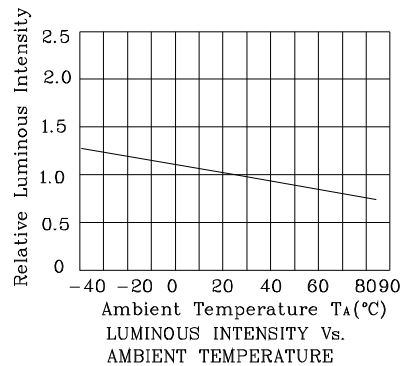
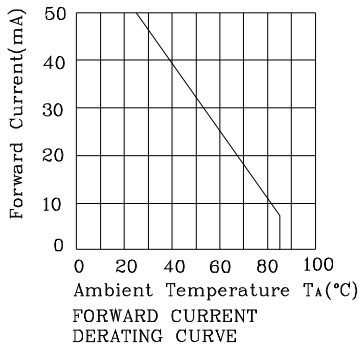
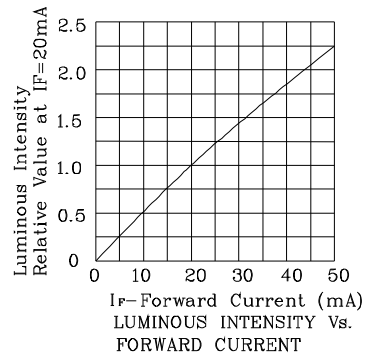
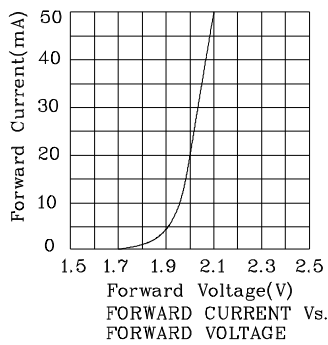
Absolute maximum ratings (TA=25°C)		MY (InGaAlP)	Unit
Reverse voltage	V _R	5	V
Forward current	I _F	50	mA
Forward current (peak) 1/10Duty cycle 0.1ms pulse width	i _{FS}	150	mA
Power dissipation	P _T	125	mW
Operating temperature	T _A	-40 ~ +85	°C
Storage temperature	T _{stg}	-40 ~ +85	

Operating Characteristics (TA=25°C)		MY (InGaAlP)	Unit
Forward voltage (typ.) (I _F =20mA)	V _F	2.0	V
Forward voltage (max.) (I _F =20mA)	V _F	2.5	V
Reverse current (V _R =5V)	I _R	10	uA
Wavelength at peak emission (I _F =20mA)	λ peak	590	nm
Wavelength at Dominate emission (I _F =20mA)	λ D	588	nm
Spectral Line half-width (I _F =20mA)	Δλ	28	nm
Capacitance (V _F =0V, f=1MHz)	C	25	pF

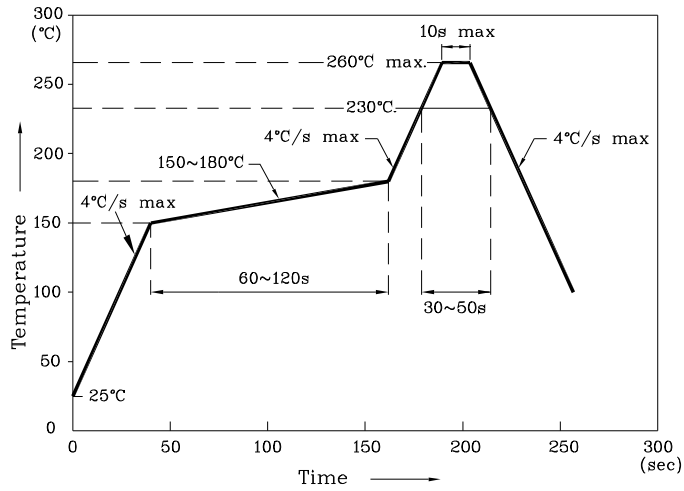
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZMY45WB	Yellow	InGaAlP	Water Clear	36	95	590	120°



❖ MY



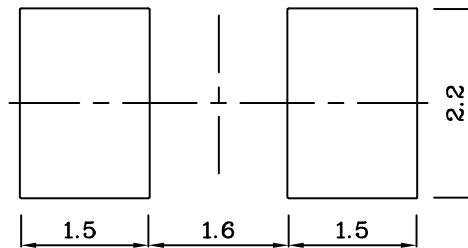
Reflow Soldering Profile For Lead-free SMT Process.



Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance:±0.1)



❖ Tape Specification (Units : mm)

